

-12A, -100V, 0.30 Ohm, P-Channel Power MOSFET

These are P-Channel enhancement mode silicon gate power field effect transistors. They are advanced power MOSFETs designed, tested, and guaranteed to withstand a specified level of energy in the breakdown avalanche mode of operation. All of these power MOSFETs are designed for applications such as switching regulators, switching convertors, motor drivers, relay drivers, and drivers for high power bipolar switching transistors requiring high speed and low gate drive power. They can be operated directly from integrated circuits.

Formerly developmental type TA17511.

Ordering Information

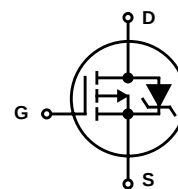
PART NUMBER	PACKAGE	BRAND
IRF9130	TO-204AA	IRF9130

NOTE: When ordering, use the entire part number.

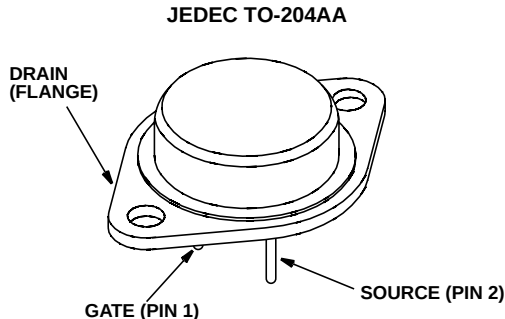
Features

- -12A, -100V
- $r_{DS(ON)} = 0.30\Omega$
- Single Pulse Avalanche Energy Rated
- SOA is Power Dissipation Limited
- Nanosecond Switching Speeds
- Linear Transfer Characteristics
- High Input Impedance

Symbol



Packaging



Absolute Maximum Ratings $T_C = 25^{\circ}\text{C}$, Unless Otherwise Specified

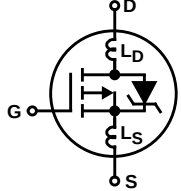
	IRF9130	UNITS
Drain to Source Breakdown Voltage (Note 1)	V_{DS} -100	V
Drain to Gate Voltage ($R_{GS} = 20\text{k}\Omega$) (Note 1)	V_{DGR} -100	V
Continuous Drain Current	I_D -12	A
$T_C = 100^{\circ}\text{C}$	I_D -7.5	A
Pulsed Drain Current (Note 3)	I_{DM} -48	A
Gate to Source Voltage	V_{GS} ± 20	V
Maximum Power Dissipation (Figure 1)	P_D 75	W
Linear Derating Factor	0.6	W/ $^{\circ}\text{C}$
Single Pulse Avalanche Energy Rating (Note 4)	E_{AS} 500	mJ
Operating and Storage Temperature	T_J, T_{STG} -55 to 150	$^{\circ}\text{C}$
Maximum Temperature for Soldering Leads at 0.063in (1.6mm) from Case for 10s.	T_L 300	$^{\circ}\text{C}$

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. $T_J = 25^{\circ}\text{C}$ to $T_J = 125^{\circ}\text{C}$.

Electrical Specifications $T_C = 25^{\circ}\text{C}$, Unless Otherwise Specified

PARAMETER	SYMBOL	TEST CONDITIONS		MIN	TYP	MAX	UNITS
Drain to Source Breakdown Voltage	BV _{DSS}	I _D = -250μA, V _{GS} = 0V, (Figure 10)		-100	-	-	V
Gate Threshold Voltage	V _{GS(TH)}	V _{GS} = V _{DS} , I _D = -250μA		-2	-	-4	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = Rated BV _{DSS} , V _{GS} = 0V		-	-	-25	μA
		V _{DS} = 0.8 x Rated BV _{DSS} , V _{GS} = 0V, T _C = 125 ^o C		-	-	250	μA
On-State Drain Current (Note 2)	I _{D(ON)}	V _{DS} > I _{D(ON)} x r _{DS(ON)MAX} , V _{GS} = -10V		-12	-	-	A
Gate to Source Leakage Current	I _{GSS}	V _{GS} = ±20V		-	-	±100	nA
Drain to Source On Resistance (Note 2)	r _{DS(ON)}	I _D = -6.5A, V _{GS} = -10V, (Figures 8, 9)		-	0.25	0.30	Ω
Forward Transconductance (Note 2)	g _{fs}	V _{DS} > I _{D(ON)} x r _{DS(ON)MAX} , I _D = -6.5A (Figure 12)		2	3.7	-	S
Turn-On Delay Time	t _{d(ON)}	V _{DD} = 0.5 x Rated BV _{DSS} , I _D ≈ -6.5A, R _G = 50Ω R _L = 5.7Ω (Figures 17, 18) MOSFET Switching Times are Essentially Independent of Operating Temperature		-	30	60	ns
Rise Time	t _r			-	70	140	ns
Turn-Off Delay Time	t _{d(OFF)}			-	70	140	ns
Fall Time	t _f			-	70	140	ns
Total Gate Charge (Gate to Source + Gate to Drain)	Q _{g(TOT)}	V _{GS} = -10V, I _D = -15A, V _{DS} = 0.8 x Rated BV _{DSS} I _{g(REF)} = -1.5mA (Figures 14, 19, 20) Gate Charge is Essentially Independent of Operating Temperature		-	25	45	nC
Gate to Source Charge	Q _{gs}			-	13	-	nC
Gate to Drain “Miller” Charge	Q _{gd}			-	12	-	nC
Input Capacitance	C _{ISS}	V _{DS} = -25V, V _{GS} = 0V, f = 1MHz (Figure 11)		-	500	-	pF
Output Capacitance	C _{OSS}			-	300	-	pF
Reverse Transfer Capacitance	C _{RSS}			-	100	-	pF
Internal Drain Inductance	L _D	Measured Between the Contact Screw on the Flange that is Closer to Source and Gate Pins and the Center of Die		-	5.0	-	nH
Internal Source Inductance	L _S	Measured From the Source Lead, 6mm (0.25in) From the Flange and the Source Bonding Pad		-	12.5	-	nH
Thermal Resistance Junction to Case	R _{θJC}			-	-	1.67	^o C/W
Thermal Resistance Junction to Ambient	R _{θJA}	Typical Socket Mount		-	-	30	^o C/W

Source to Drain Diode Specifications

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Continuous Source to Drain Current	I_{SD}	Modified MOSFET Symbol Showing the Integral Reverse P-N Junction Diode	-	-	-12	A
Pulse Source to Drain Current (Note 3)	I_{SDM}		-	-	-48	A
Source to Drain Diode Voltage (Note 2)	V_{SD}	$T_C = 25^{\circ}\text{C}$, $I_{SD} = -12\text{A}$, $V_{GS} = 0\text{V}$ (Figure 13)	-	-	-1.5	V
Reverse Recovery Time	t_{rr}	$T_J = 150^{\circ}\text{C}$, $I_{SD} = -12\text{A}$, $dI_{SD}/dt = 100\text{A}/\mu\text{s}$	-	300	-	ns
Reverse Recovery Charge	Q_{RR}	$T_J = 150^{\circ}\text{C}$, $I_{SD} = -12\text{A}$, $dI_{SD}/dt = 100\text{A}/\mu\text{s}$	-	1.8	-	μC

NOTES:

- Pulse test: pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
- Repetitive rating: pulse width limited by maximum junction temperature. See Transient Thermal Impedance curve (Figure 3).
- $V_{DD} = 25\text{V}$, starting $T_J = 25^{\circ}\text{C}$, $L = 5.2\text{mH}$, $R_G = 25\Omega$, peak $I_{AS} = 12\text{A}$. See Figures 15, 16.

Typical Performance Curves Unless Otherwise Specified

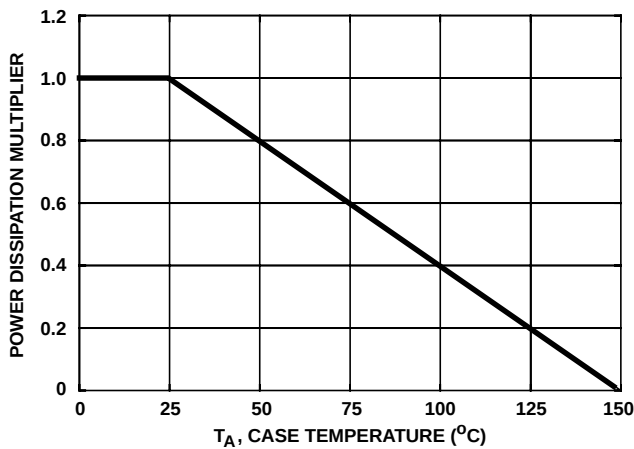


FIGURE 1. NORMALIZED POWER DISSIPATION vs CASE TEMPERATURE

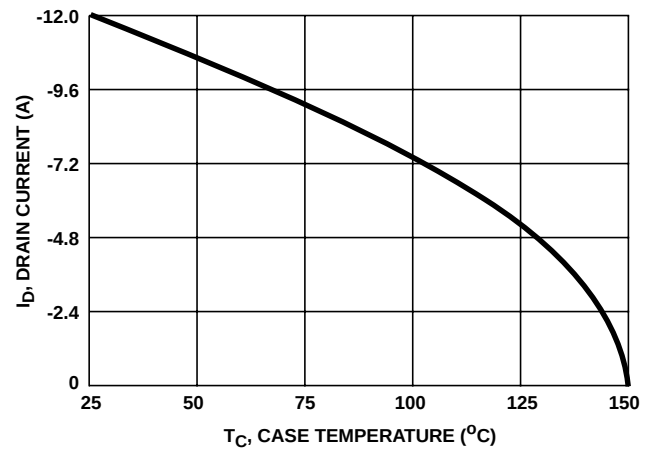


FIGURE 2. MAXIMUM CONTINUOUS DRAIN CURRENT vs CASE TEMPERATURE

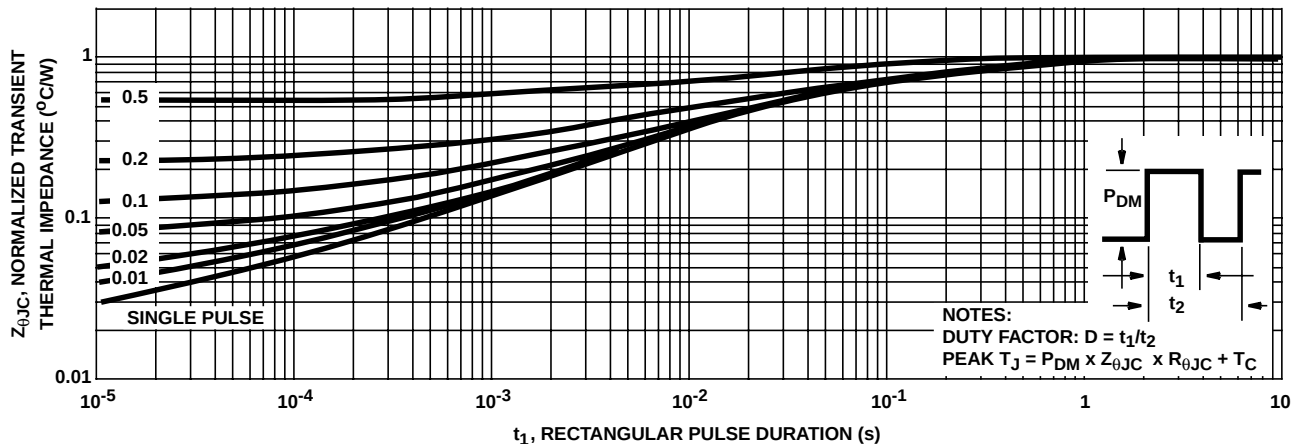


FIGURE 3. NORMALIZED MAXIMUM TRANSIENT THERMAL IMPEDANCE

Typical Performance Curves Unless Otherwise Specified (Continued)

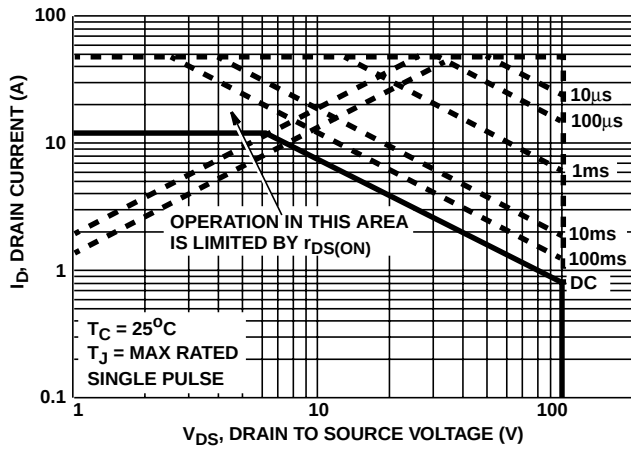


FIGURE 4. FORWARD BIAS SAFE OPERATING AREA

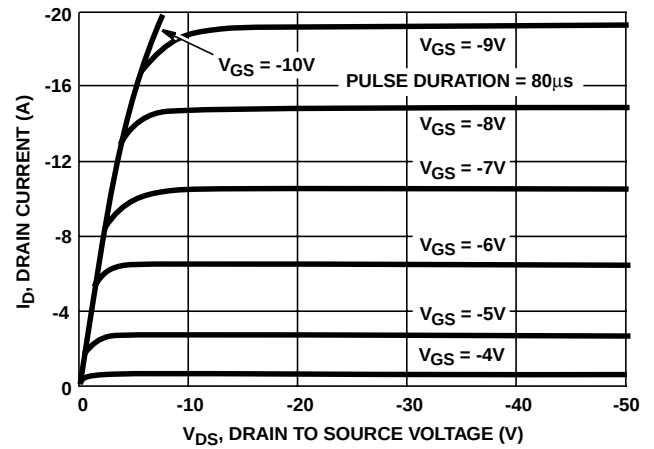


FIGURE 5. OUTPUT CHARACTERISTICS

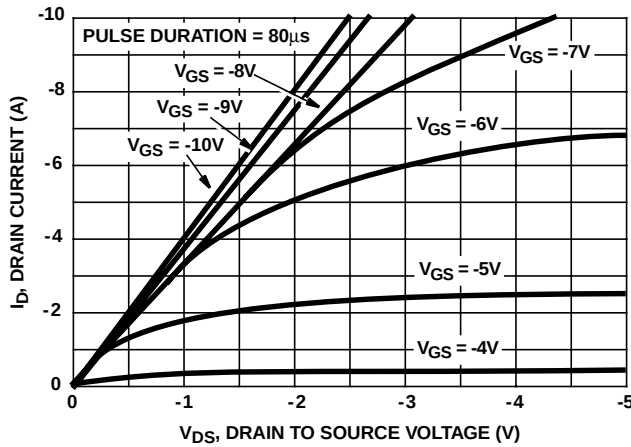


FIGURE 6. SATURATION CHARACTERISTICS

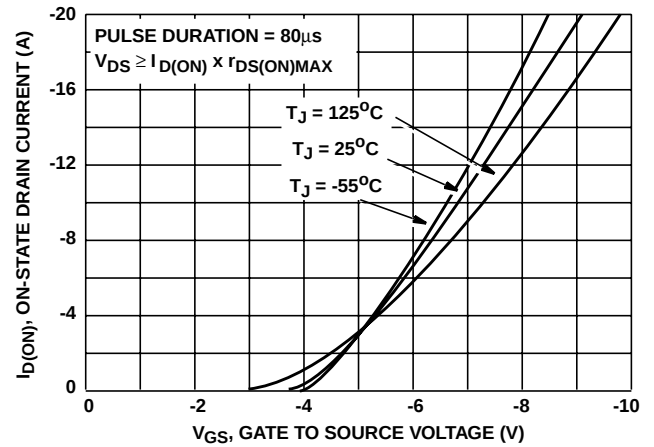
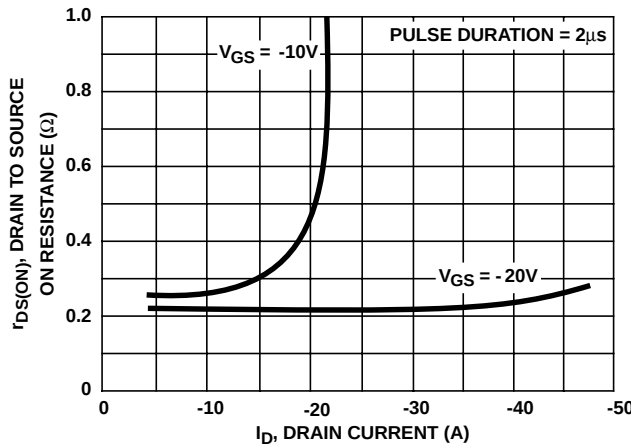


FIGURE 7. TRANSFER CHARACTERISTICS



NOTE: Heating effect of 2μs pulse is minimal.

FIGURE 8. DRAIN TO SOURCE ON RESISTANCE vs GATE VOLTAGE AND DRAIN CURRENT

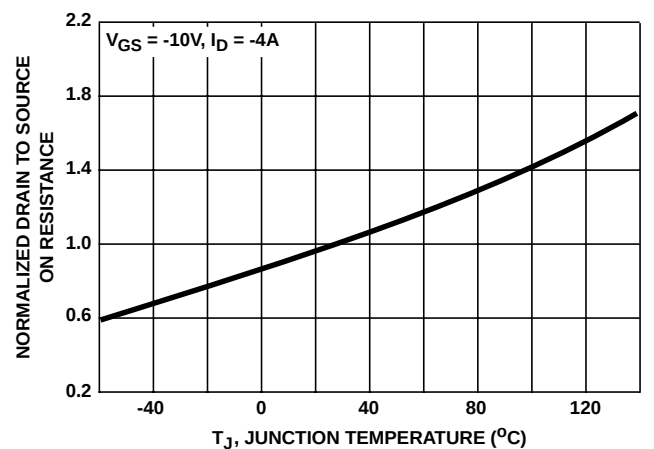


FIGURE 9. NORMALIZED DRAIN TO SOURCE ON RESISTANCE vs JUNCTION TEMPERATURE

Typical Performance Curves Unless Otherwise Specified (Continued)

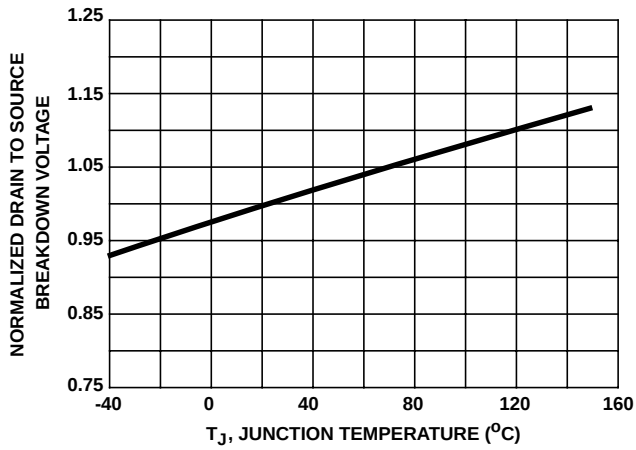


FIGURE 10. NORMALIZED DRAIN TO SOURCE BREAKDOWN VOLTAGE vs JUNCTION TEMPERATURE

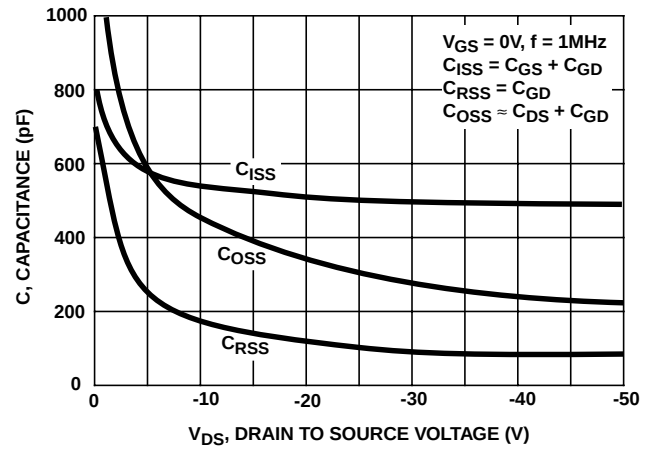


FIGURE 11. CAPACITANCE vs DRAIN TO SOURCE VOLTAGE

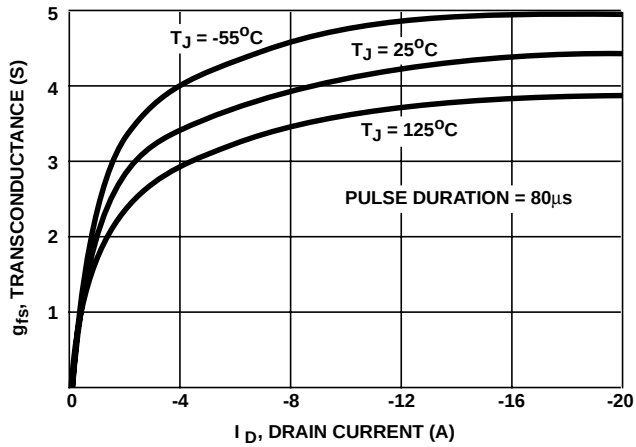


FIGURE 12. TRANSCONDUCTANCE vs DRAIN CURRENT

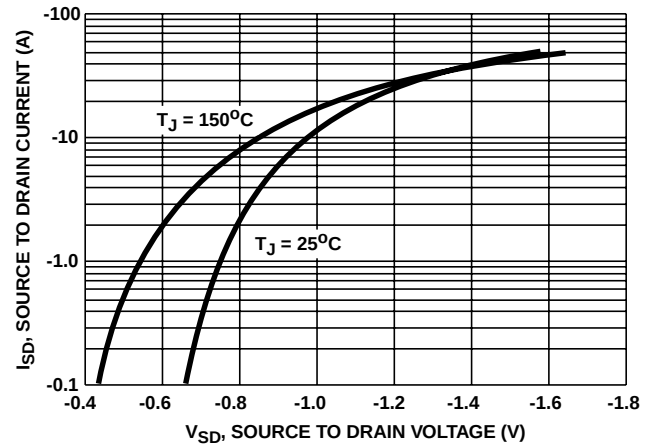


FIGURE 13. SOURCE TO DRAIN DIODE VOLTAGE

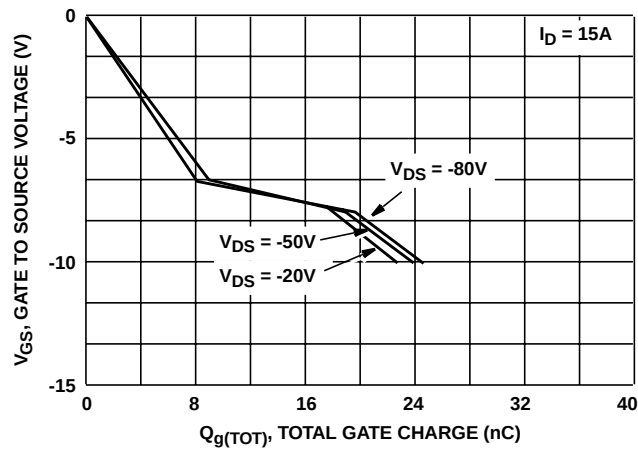


FIGURE 14. GATE TO SOURCE VOLTAGE vs GATE CHARGE

Test Circuits and Waveforms

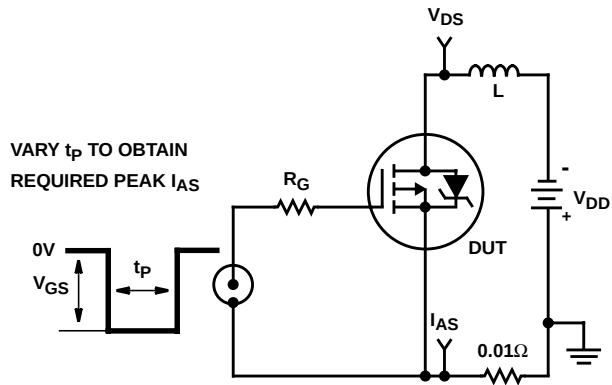


FIGURE 15. UNCLAMPED ENERGY TEST CIRCUIT

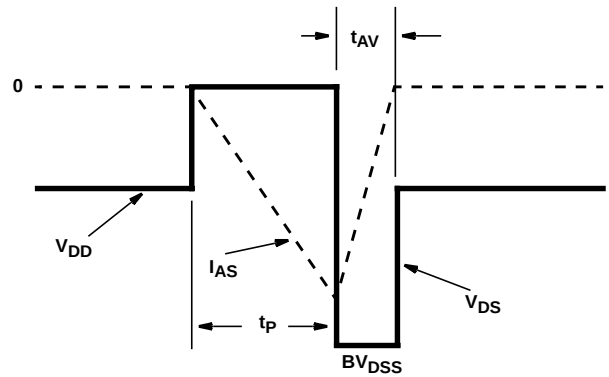


FIGURE 16. UNCLAMPED ENERGY WAVEFORMS

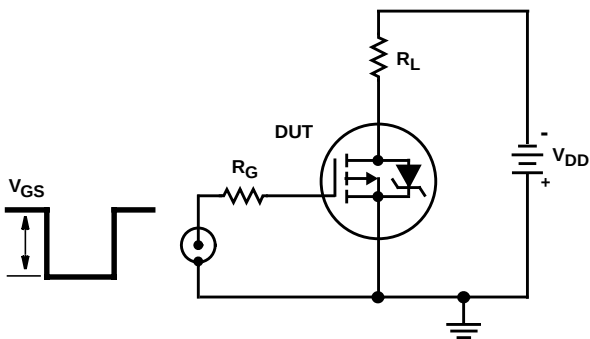


FIGURE 17. SWITCHING TIME TEST CIRCUIT

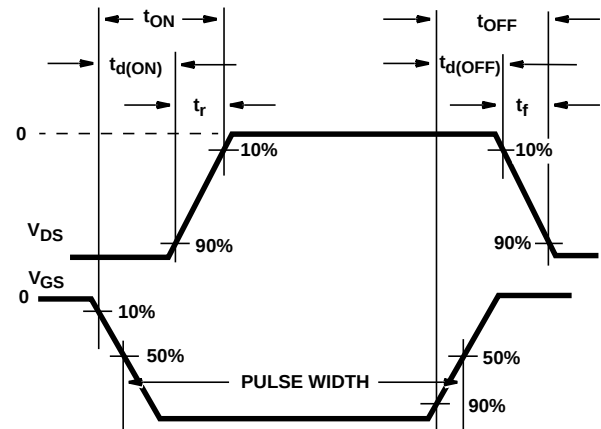


FIGURE 18. RESISTIVE SWITCHING WAVEFORMS

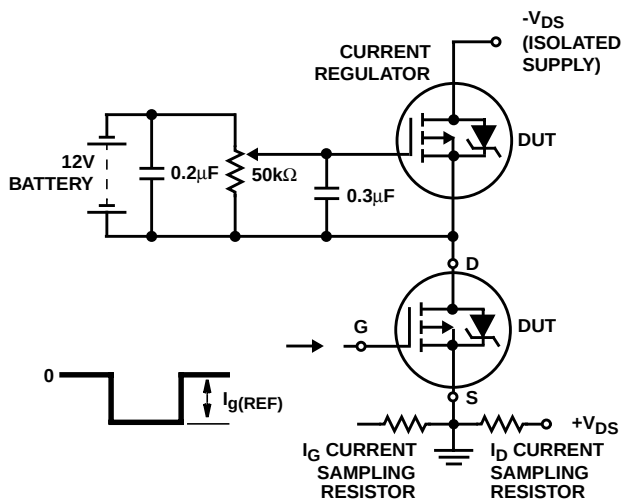


FIGURE 19. GATE CHARGE TEST CIRCUIT

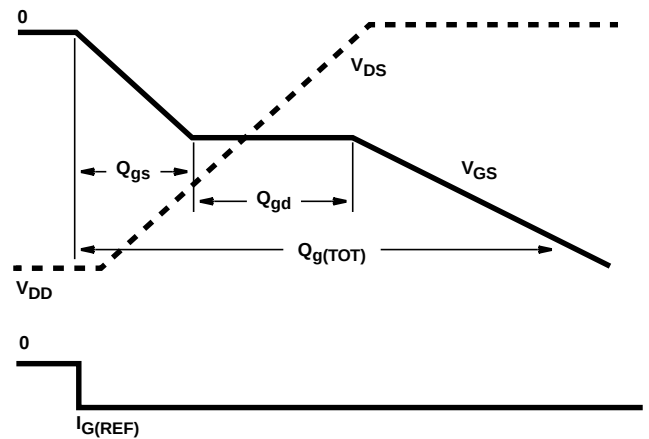


FIGURE 20. GATE CHARGE WAVEFORMS

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